

**P-Channel MOSFET  
20V 4.5A SOT-23 AEC-Q101**

MFT2P4A5S23EA

MERITEK

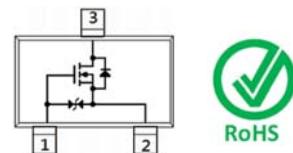
## FEATURE

- $R_{DS(ON)} < 48m\Omega$ ,  $V_{GS} = -4.5V$ ,  $I_D = 4.5A$
- $R_{DS(ON)} < 60m\Omega$ ,  $V_{GS} = -2.5V$ ,  $I_D = 3A$
- $R_{DS(ON)} < 88m\Omega$ ,  $V_{GS} = -1.8V$ ,  $I_D = 1.5A$
- Advanced Trench Process Technology
- Application: Switch Load, PWM Application, etc.
- ESD Protected 2KV HBM
- AEC-Q101 Qualified



## MECHANICAL DATA

- Case: SOT-23 Package
- Terminals: Solderable per MIL-STD-750, Method 2026

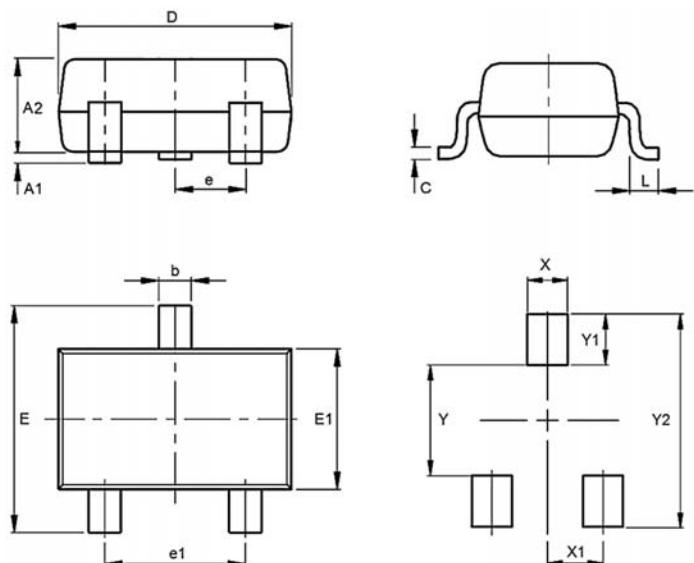


## MAXIMUM RATINGS

Parameter		Symbol	Value	Unit
Drain-Source Voltage		$V_{DS}$	-20	V
Gate-Source Voltage		$V_{GS}$	$\pm 8$	V
Drain Current – Continuous	$T_A = 25^\circ C$	$I_D$	-4.3	A
Drain Current – Pulsed		$I_{DM}$	-17.2	A
Power Dissipation	$T_A = 25^\circ C$	$P_D$	1.25	W
	Derate above $25^\circ C$		10	mW/ $^\circ C$
Thermal Resistance Junction to Ambient		$R_{\theta JA}$	100	$^\circ C/W$
Operating Junction and Storage Temperature		$T_J, T_{STG}$	-55 to 150	$^\circ C$

## DIMENSIONS

Item	Min (mm)	Max (mm)
A1	0.00	0.10
A2	0.90	1.10
b	0.35	0.50
C	0.08	0.20
D	2.80	3.04
e	0.90	1.00
e1	1.80	2.00
E	2.20	2.60
E1	1.20	1.40
L	0.15	
X	0.80	
X1	0.95	
Y	1.10	
Y1	0.90	
Y2	2.90	



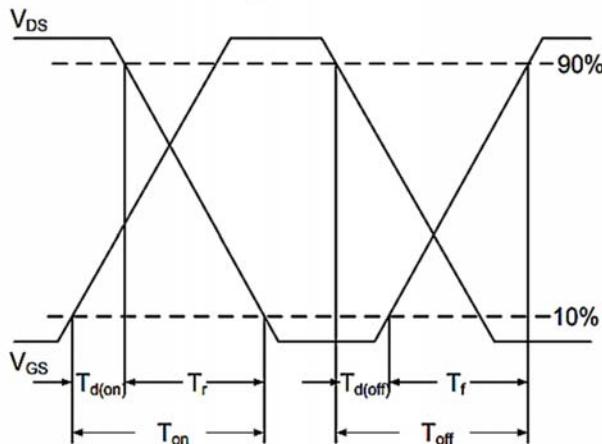
## ELECTRICAL CHARACTERISTICS

Off Characteristics	Conditions	Symbol	Min	Typ.	Max	Unit
Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=-250\mu A$	$BV_{DSS}$	-20	--	--	V
Drain-Source Leakage Current	$V_{DS}=-20V, V_{GS}=0V$	$I_{DSS}$	--	--	-1	$\mu A$
Gate-Source Leakage Current	$V_{GS}=\pm 8V, V_{DS}=0V$	$I_{GSS}$	--	--	$\pm 10$	$\mu A$
On Characteristics	Conditions	Symbol	Min	Typ.	Max	Unit
Static Drain-Source On-Resistance	$V_{GS}=-4.5V, I_D=-4.3A$	$R_{DS(ON)}$	--	44	52	$m\Omega$
	$V_{GS}=-2.5V, I_D=-3.0A$		--	53	60	
	$V_{GS}=-1.8V, I_D=-1.5A$		--	70	80	
Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=-250\mu A$	$V_{GS(th)}$	-0.4	-0.72	-1.0	V
Dynamic Characteristics	Conditions	Symbol	Min	Typ.	Max	Unit
Total Gate Charge	$V_{DS}=-10V, V_{GS}=-4.5V, I_D=-4.3A$	$Q_g$	--	24	--	$nC$
Gate-Source Charge		$Q_{gs}$	--	1.5	--	
Gate-Drain Charge		$Q_{gd}$	--	2.5	--	
Turn-On Delay Time	$V_{DD}=-10V, V_{GS}=-4.5V, R_G=6\Omega$ $I_D=-4.3A$	$T_{d(on)}$	--	45	--	$ns$
Rise Time		$T_r$	--	79	--	
Turn-Off Delay Time		$T_{d(off)}$	--	193	--	
Fall Time		$T_f$	--	826	--	
Input Capacitance	$V_{DS}=-10V, V_{GS}=0V, f=1MHz$	$C_{iss}$	--	907	--	$pF$
Output Capacitance		$C_{oss}$	--	90	--	
Reverse Transfer Capacitance		$C_{rss}$	--	70	--	
Drain-Source Body Diode	Conditions	Symbol	Min	Typ.	Max	Unit
Continuous Source Current	$V_G=V_D=0V$ , Force Current	$I_s$	--	--	-1.5	A
Diode Forward Voltage	$V_{GS}=0V, I_s=-1.0A$	$V_{SD}$	--	-0.76	-1.2	V

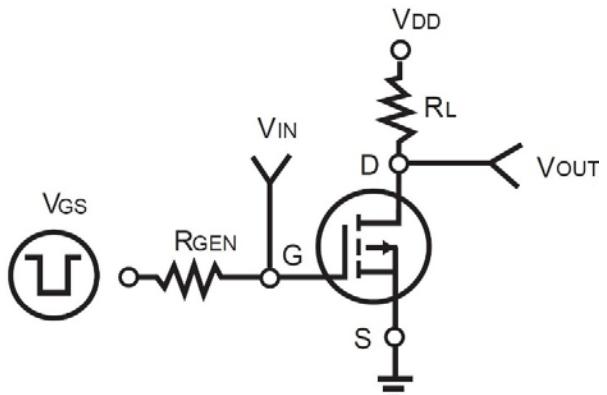
Note:

1. Pulse width $\leq 300\mu s$ , Duty cycle $\leq 2\%$
2. Essentially independent of operating temperature typical characteristics
3. Maximum current rating is package limited
4.  $R_{QJA}$  is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. Mounted on a 1 inch $^2$  with 2oz square pad of copper.
5. Guaranteed by design, not subject to production testing.

Switching Time Waveform

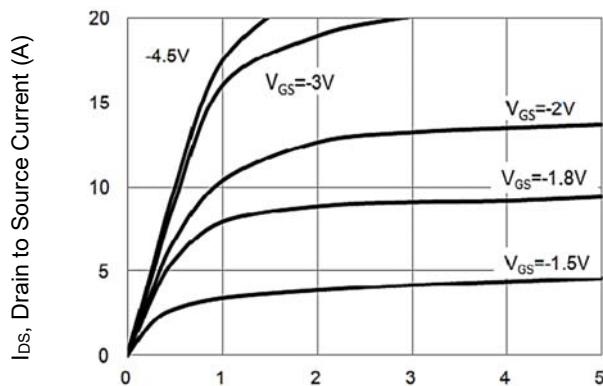


Switching Test Circuit



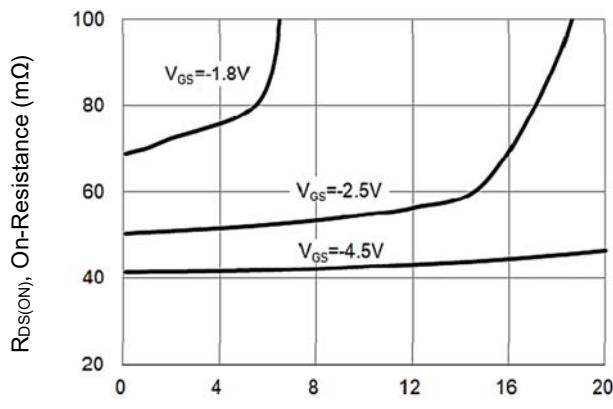
## CHARACTERISTIC CURVES

On-Region Characteristics



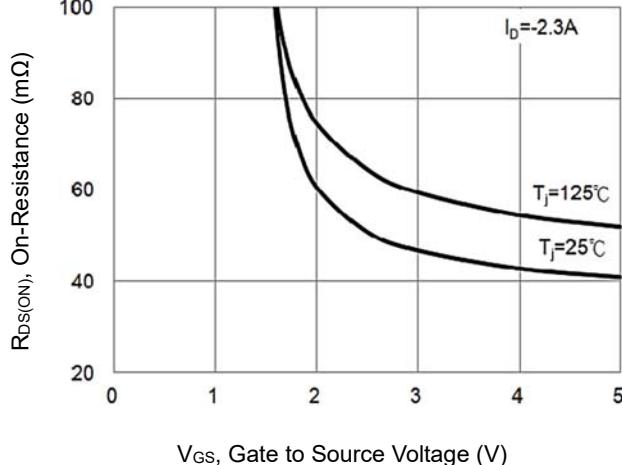
$V_{DS}$ , Drain to Source Voltage (V)

On-Resistance vs. Drain Current



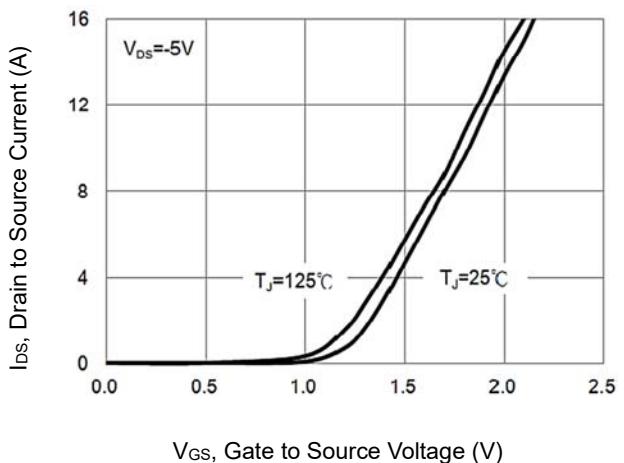
$I_{DS}$ , Drain to Source Current (A)

On-Resistance Variation with  $V_{GS}$



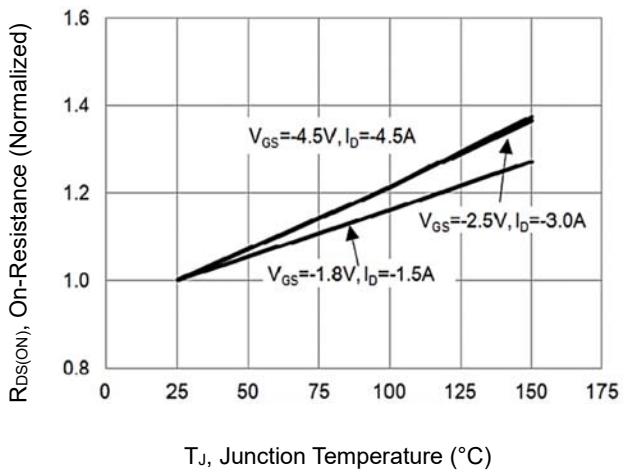
$V_{GS}$ , Gate to Source Voltage (V)

Transfer Characteristics



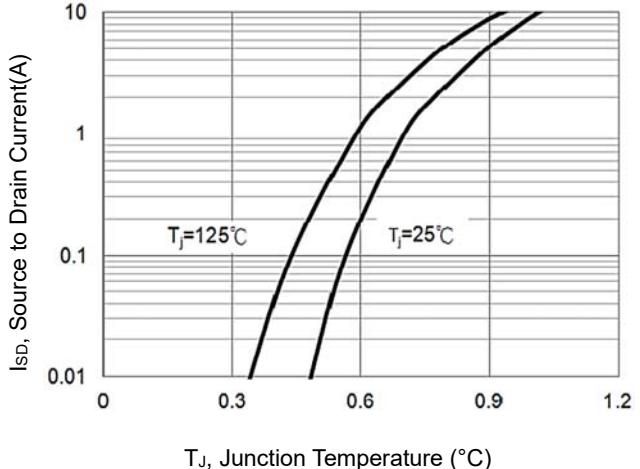
$V_{GS}$ , Gate to Source Voltage (V)

On-Resistance vs. Junction Temperature



$T_J$ , Junction Temperature ( $^\circ C$ )

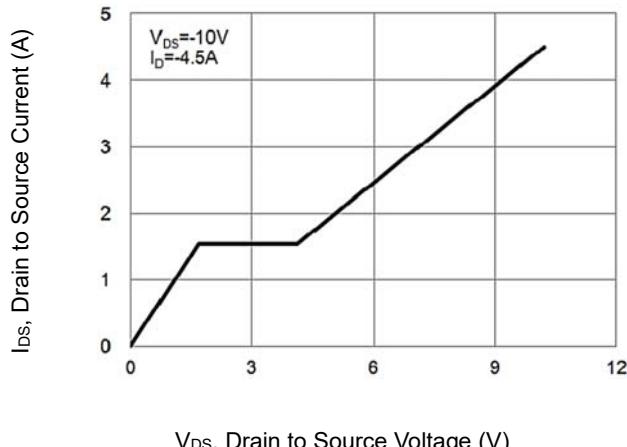
Bode Diode Characteristics



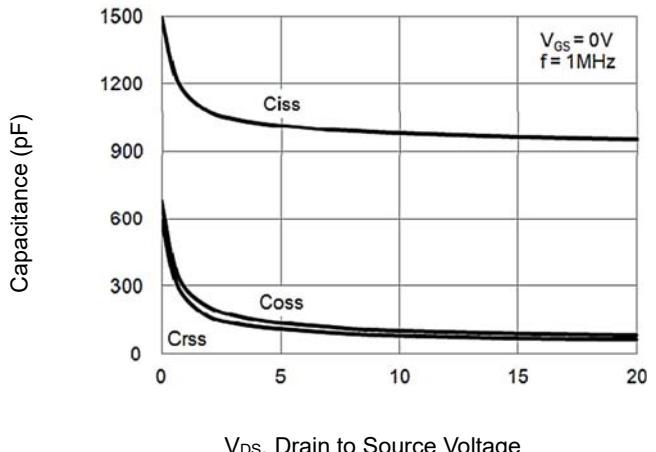
$T_J$ , Junction Temperature ( $^\circ C$ )

## CHARACTERISTICS CURVES

Gate-Charge Characteristics



Capacitance vs. Drain to Source Voltage



Threshold Voltage Variation with Temperature

